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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	8064
Number of Logic Elements/Cells	-
Total RAM Bits	73728
Number of I/O	115
Number of Gates	500000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-55°C ~ 125°C (TA)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax500-1pq208m

5 V Tolerance

There are two schemes to achieve 5 V tolerance:

1. 3.3 V PCI and 3.3 V PCI-X are the only I/O standards that directly allow 5 V tolerance. To implement this, an internal clamp diode between the input pad and the VCCI pad is enabled so that the voltage at the input pin is clamped, as shown in EQ 3:

$$V_{\text{input}} = V_{\text{CCI}} + V_{\text{diode}} = 3.3 \text{ V} + 0.7 \text{ V} = 4.0 \text{ V}$$

EQ 3

The internal VCCI clamp diode is only enabled while the device is powered on, so the voltage at the input will not be clamped if the VCCI or VCCA are powered off. An external series resistor (~100 Ω) is required between the input pin and the 5 V signal source to limit the current to less than 20 mA (Figure 2-3). The 100 Ω resistor was chosen to meet the input Tr/Tf requirement (Table 2-19 on page 2-21). The GND clamp diode is available for all I/O standards and always enabled.

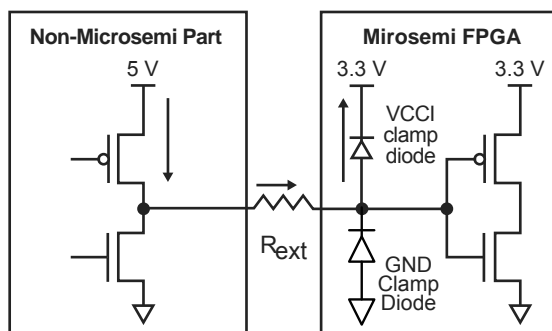


Figure 2-3 • Use of an External Resistor for 5 V Tolerance

2. 5 V tolerance can also be achieved with 3.3 V I/O standards (3.3 V PCI, 3.3 V PCI-X, and LVTTTL) using a bus-switch product (e.g. IDTQS32X2384). This will convert the 5 V signal to a 3.3 V signal with minimum delay (Figure 2-4).

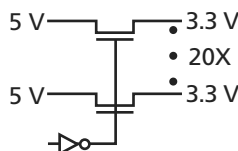


Figure 2-4 • Bus Switch IDTQS32X2384

Simultaneous Switching Outputs (SSO)

When multiple output drivers switch simultaneously, they induce a voltage drop in the chip/package power distribution. This simultaneous switching momentarily raises the ground voltage within the device relative to the system ground. This apparent shift in the ground potential to a non-zero value is known as simultaneous switching noise (SSN) or more commonly, ground bounce.

SSN becomes more of an issue in high pin count packages and when using high performance devices such as the Axcelerator family. Based upon testing, Microsemi recommends that users not exceed eight simultaneous switching outputs (SSO) per each VCCI/GND pair. To ease this potential burden on designers, Microsemi has designed all of the Axcelerator BGAs³ to not exceed this limit with the exception of the CS180, which has an I/O to VCCI/GND pair ratio of nine to one.

Please refer to the *Simultaneous Switching Noise and Signal Integrity* application note for more information.

3. The user should note that in Bank 8 of both AX1000-FG484 and AX500-FG484, there are local violations of this 8:1 ratio.

Table 2-13 summarizes the different combinations of voltages and I/O standards that can be used together in the same I/O bank.

Table 2-13 • Legal I/O Usage Matrix

I/O Standard	LVTTTL 3.3 V	LVC MOS 2.5 V	LVC MOS 1.8 V	LVC MOS 1.5 V (JESD8-11)	3.3 V PCI/PCI-X	GTL + (3.3 V)	GTL + (2.5 V)	HSTL Class I (1.5V)	SSTL2 Class I & II (2.5 V)	SSTL3 Class I & II (3.3 V)	LVDS (2.5 V)	LVPECL (3.3 V)
LVTTTL 3.3 V (VREF=1.0 V)	✓	–	–	–	✓	✓	–	–	–	–	–	✓
LVTTTL 3.3 V (VREF=1.5 V)	✓	–	–	–	✓	–	–	–	–	✓	–	✓
LVC MOS 2.5 V (VREF=1.0 V)	–	✓	–	–	–	–	✓	–	–	–	✓	–
LVC MOS 2.5 V (VREF=1.25V)	–	✓	–	–	–	–	–	–	✓	–	✓	–
LVC MOS 1.8 V	–	–	✓	–	–	–	–	–	–	–	–	–
LVC MOS 1.5 V (VREF = 1.75 V) (JESD8-11)	–	–	–	✓	–	–	–	✓	–	–	–	–
3.3 V PCI/PCI-X (VREF = 1.0 V)	✓	–	–	–	✓	✓	–	–	–	–	–	✓
3.3 V PCI/PCI-X (VREF= 1.5 V)	✓	–	–	–	✓	–	–	–	–	✓	–	✓
GTL + (3.3 V)	✓	–	–	–	✓	✓	–	–	–	–	–	✓
GTL + (2.5 V)	–	✓	–	–	–	–	✓	–	–	–	–	–
HSTL Class I	–	–	–	✓	–	–	–	✓	–	–	–	–
SSTL2 Class I & II	–	✓	–	–	–	–	–	–	✓	–	✓	–
SSTL3 Class I & II	✓	–	–	–	✓	–	–	–	–	✓	–	✓
LVDS (VREF = 1.0 V)	–	✓	–	–	–	–	✓	–	–	–	✓	–
LVDS (VREF = 1.25 V)	–	✓	–	–	–	–	–	–	✓	–	✓	–
LVPECL (VREF = 1.0 V)	✓	–	–	–	✓	✓	–	–	–	–	–	✓
LVPECL (VREF = 1.5 V)	✓	–	–	–	✓	–	–	–	–	✓	–	✓

Notes:

1. Note that GTL+ 2.5 V is not supported across the full military temperature range.
2. A "✓" indicates whether standards can be used within a bank at the same time.

Examples:

- a) LVTTTL can be used with 3.3V PCI and GTL+ (3.3V), when $V_{REF} = 1.0V$ (GTL+ requirement).
- b) LVTTTL can be used with 3.3V PCI and SSTL3 Class I and II, when $V_{REF} = 1.5V$ (SSTL3 requirement).

Note that two I/O standards are compatible if:

- Their VCCI values are identical.
- Their VREF standards are identical (if applicable).

For example, if LVTTTL 3.3 V (VREF= 1.0 V) is used, then the other available (i.e. compatible) I/O standards in the same bank are LVTTTL 3.3 V PCI/PCI-X, GTL+, and LVPECL.

Also note that when multiple I/O standards are used within a bank, the voltage tolerance will be limited to the minimum tolerance of all I/O standards used in the bank.

3.3 V LVTTTL

Low-Voltage Transistor-Transistor Logic is a general purpose standard (EIA/JESD) for 3.3 V applications. It uses an LVTTTL input buffer and push-pull output buffer.

Table 2-20 • DC Input and Output Levels

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA
-0.3	0.8	2.0	3.6	0.4	2.4	24	-24

AC Loadings

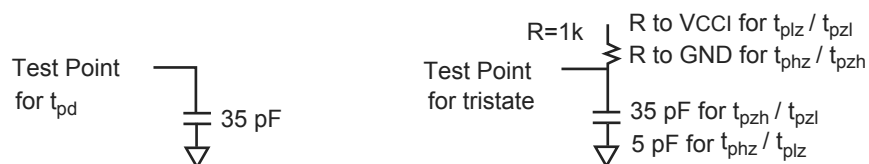


Figure 2-15 • AC Test Loads

Table 2-21 • AC Waveforms, Measuring Points, and Capacitive Load

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C _{load} (pF)
0	3.0	1.40	N/A	35

Note: * Measuring Point = VTRIP

1.8 V LVCMOS

Low-Voltage Complementary Metal-Oxide Semiconductor for 1.8 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 1.8 V applications. It uses a 3.3 V tolerant CMOS input buffer and a push-pull output buffer.

Table 2-26 • DC Input and Output Levels

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA
-0.3	0.2 VCCI	0.7 VCCI	3.6	0.2	VCCI - 0.2	8 mA	-8 mA

AC Loadings

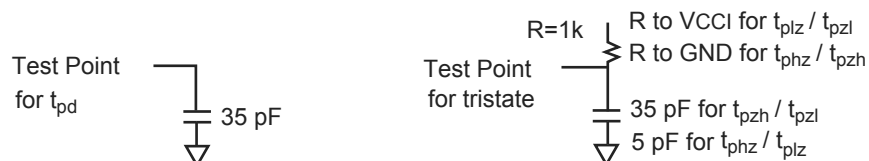


Figure 2-17 • AC Test Loads

Table 2-27 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C _{load} (pF)
0	1.8	0.5 VCCI	N/A	35

Note: * Measuring Point = VTRIP

Routing Specifications

Routing Resources

The routing structure found in Axcelerator devices enables any logic module to be connected to any other logic module while retaining high performance. There are multiple paths and routing resources that can be used to route one logic module to another, both within a SuperCluster and elsewhere on the chip.

There are four primary types of routing within the AX architecture: DirectConnect, CarryConnect, FastConnect, and Vertical and Horizontal Routing.

DirectConnect

DirectConnects provide a high-speed connection between an R-cell and its adjacent C-cell (Figure 2-35). This connection can be made from DCOUT of the C-cell to DCIN of the R-cell by configuring of the S1 line of the R-cell. This provides a connection that does not require an antifuse and has a delay of less than 0.1 ns.

Figure 2-35 • DirectConnect and CarryConnect

CarryConnect

CarryConnects are used to build carry chains for arithmetic functions (Figure 2-35). The FCO output of the right C-cell of a two-C-cell Cluster drives the FCI input of the left C-cell in the two-C-cell Cluster immediately below it. This pattern continues down both sides of each SuperCluster column.

Similar to the DirectConnects, CarryConnects can be built without an antifuse connection. This connection has a delay of less than 0.1 ns from the FCO of one two-C-cell cluster to the FCI of the two-C-cell cluster immediately below it (see the "Carry-Chain Logic" section on page 2-56 for more information).

FastConnect

For high-speed routing of logic signals, FastConnects can be used to build a short distance connection using a single antifuse (Figure 2-36 on page 2-62). FastConnects provide a maximum delay of 0.3 ns. The outputs of each logic module connect directly to the Output Tracks within a SuperCluster. Signals on the Output Tracks can then be routed through a single antifuse connection to drive the inputs of logic modules either within one SuperCluster or in the SuperCluster immediately below it.

CLK1 and CLK2

Both PLL outputs, CLK1 and CLK2, can be used to drive a global resource, an adjacent PLL RefCLK input, or a net in the FPGA core. Not all drive combinations are possible (Table 2-81).

Table 2-81 • PLL General Connections Rules

CLK1	CLK2
HCLK	HCLK
CLK	CLK
HCLK	Routed net output
Routed net output	HCLK
HCLK	NONE
NONE	HCLK
CLK	NONE
NONE	CLK

Note: The PLL outputs remain Low when REFCLK is constant (either Low or High).

Restrictions on CLK1 and CLK2

- When both are driving global resources, they must be driving the same *type* of global resource (i.e. either HCLK or CLK).
- Only one can drive a routed net at any given time.

Table 2-82 and Table 2-83 specify all the possible CLK1 and CLK2 connections for the north and south PLLs. HCLK1 and HCLK2 are used to denote the different HCLK networks when two are being driven at the same time by a single PLL (Note that HCLK1 is the primary clock resource associated with the PLL, and HCLK2 is the clock resource associated with the adjacent PLL). Likewise, CLK1 and CLK2 are used to denote the different CLK networks when two are being driven at the same time by a single PLL (Figure 2-48 on page 2-75).

Table 2-82 • North PLL Connections

CLK1	CLK2
HCLK1	Routed net
HCLK1	Unused
HCLK2	HCLK1
HCLK2	Routed net
HCLK2	Both HCLK1 and routed net
HCLK2	Unused
Unused	HCLK1
Unused	Routed net
Unused	Both HCLK1 and routed net
Unused	Unused
Routed net	HCLK1
Routed net	Unused
Both HCLK1 and HCLK2	Routed net
Both HCLK1 and HCLK2	Unused
Both HCLK1 and routed net	Unusable
Both HCLK2 and routed net	HCLK1
Both HCLK2 and routed net	Unused
HCLK1, HCLK2, and routed net	Unusable

Note: Designer software currently does not support all of these connections. Only exclusive connections where one output connects to a single net are supported at this time (e.g. CLK1 driving HCLK1, and HCLK2 is not supported).

Table 2-83 • South PLL Connections

CLK1	CLK2
CLK1	Routed net
CLK1	Unused
CLK2	CLK1
CLK2	Routed net
CLK2	Both CLK1 and routed net
CLK2	Unused
Unused	CLK1
Unused	Routed net
Unused	Both CLK1 and routed net
Unused	Unused
Routed net	CLK1
Routed net	Unused
Both CLK1 and CLK2	Routed net
Both CLK1 and CLK2	Unused
Both CLK1 and routed net	Unusable
Both CLK2 and routed net	CLK1
Both CLK2 and routed net	Unused
CLK1, CLK2, and routed net	Unusable

Note: Designer software currently does not support all of these connections. Only exclusive connections where one output connects to a single net are supported at this time (e.g., CLK1 driving both CLK1 and CLK2 is not supported).

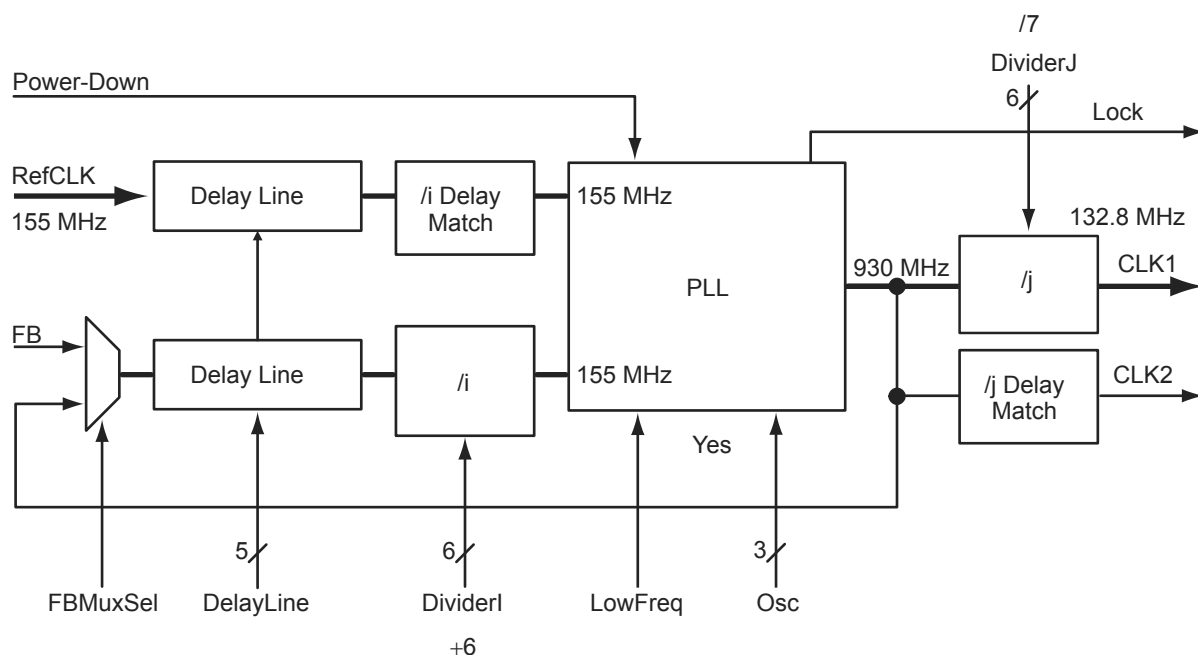


Figure 2-54 • Using the PLL 155 MHz In, 133 MHz Out

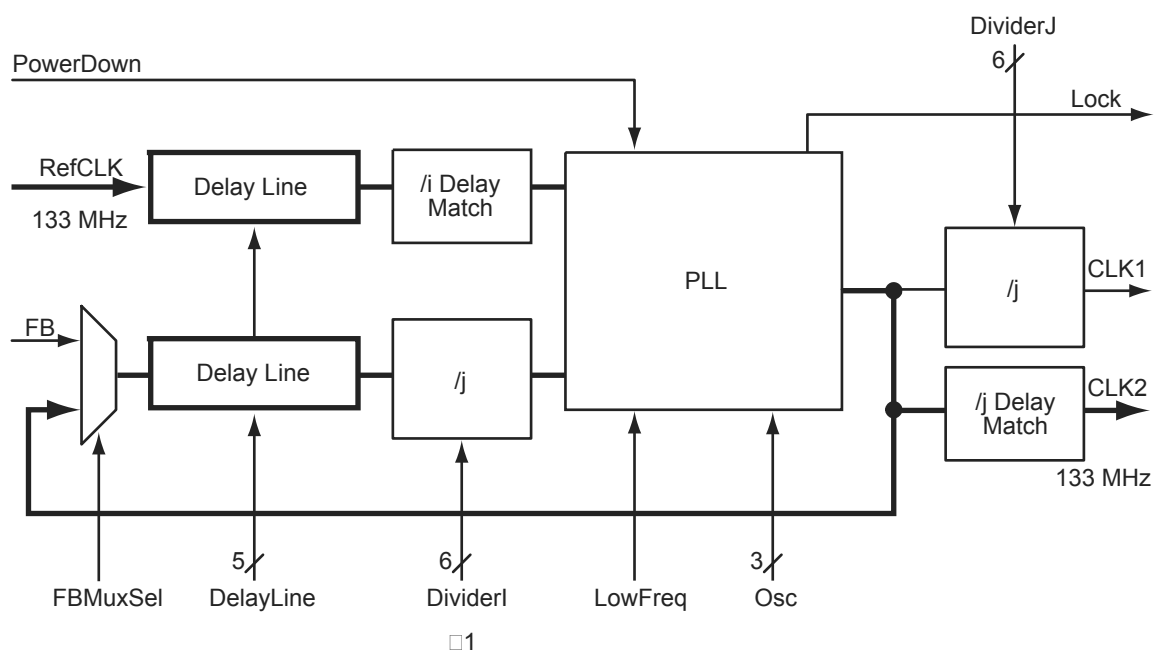


Figure 2-55 • Using the PLL Delaying the Reference Clock

Timing Characteristics

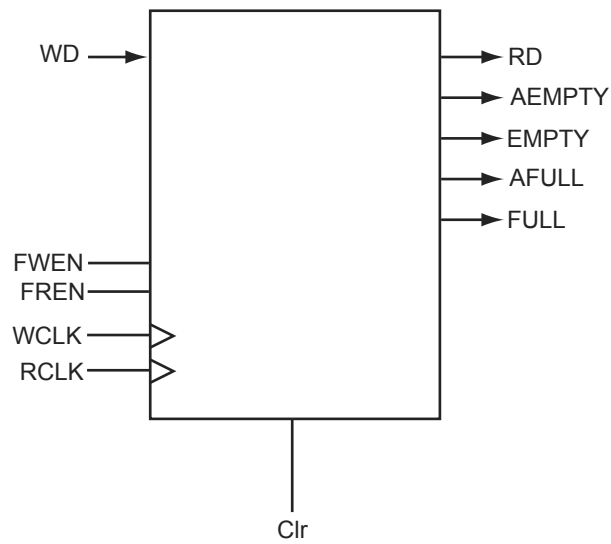


Figure 2-66 • FIFO Model

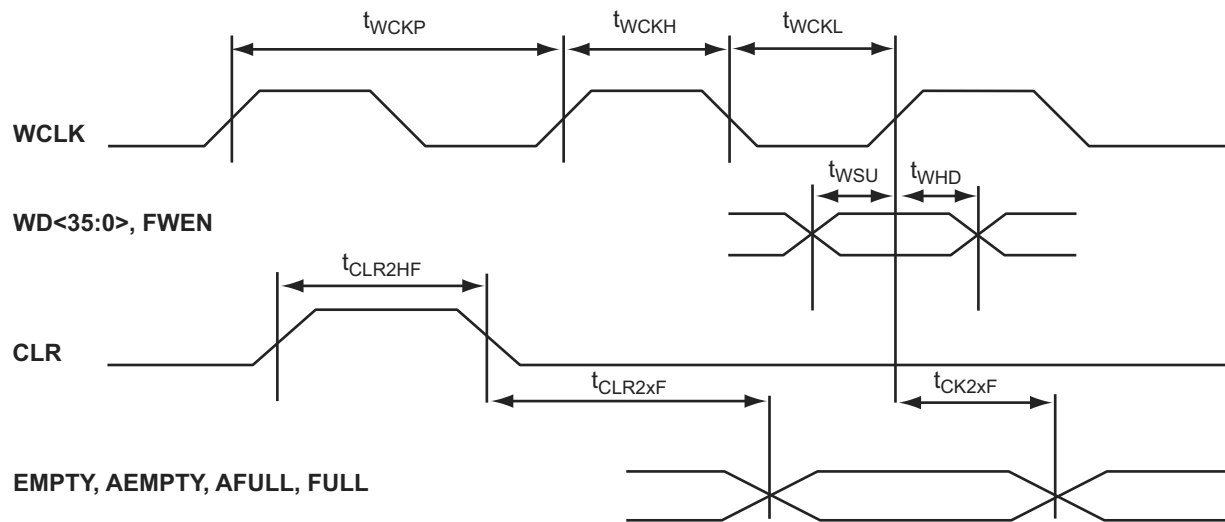


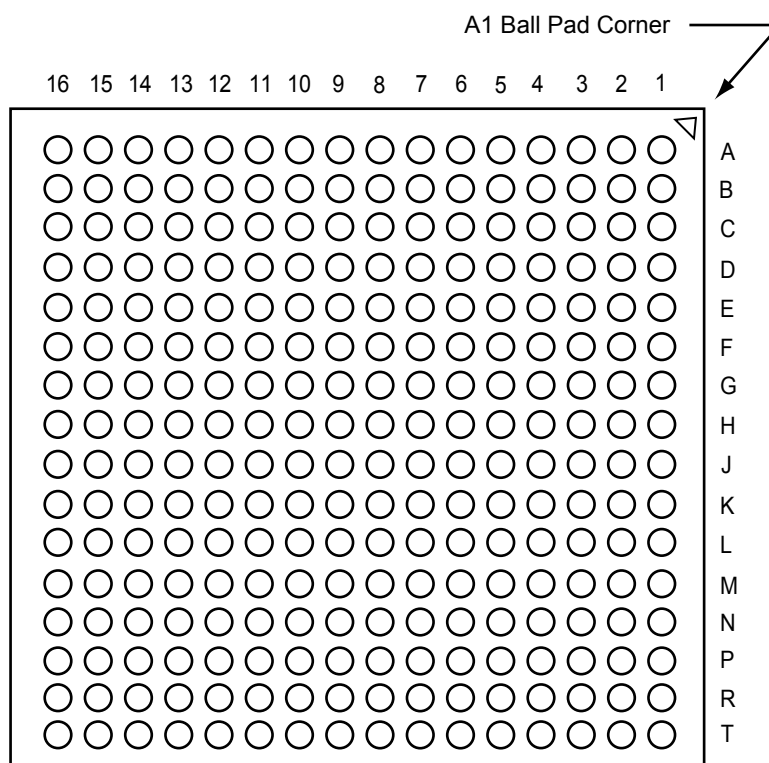
Figure 2-67 • FIFO Write Timing

Table 2-101 • Eight FIFO Blocks Cascaded
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		Units
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	
FIFO Module Timing								
t _{WSU}	Write Setup		15.46		17.61		20.70	ns
t _{WHD}	Write Hold		0.00		0.00		0.00	ns
t _{WCKH}	WCLK High		0.75		0.75		0.75	ns
t _{WCKL}	WCLK Low		5.13		5.13		5.13	ns
t _{WCKP}	Minimum WCLK Period	5.88		5.88		5.88		ns
t _{RSU}	Read Setup		16.22		18.47		21.72	ns
t _{RHD}	Read Hold		0.00		0.00		0.00	ns
t _{RCKH}	RCLK High		0.73		0.73		0.73	ns
t _{RCKL}	RCLK Low		5.77		5.77		5.77	ns
t _{RCKP}	Minimum RCLK period	6.50		6.50		6.50		ns
t _{CLRHF}	Clear High		0.00		0.00		0.00	ns
t _{CLR2FF}	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t _{CLR2AF}	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t _{CK2FF}	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t _{CK2AF}	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
t _{RCK2RD1}	RCLK-To-OUT (Pipelined)		3.39		3.86		4.54	ns
t _{RCK2RD2}	RCLK-To-OUT (Nonpipelined)		4.93		5.62		6.61	ns

Note: Timing data for these eight cascaded FIFO blocks uses a depth of 32,768. For all other combinations, use Microsemi's timing software.

FG256



Note

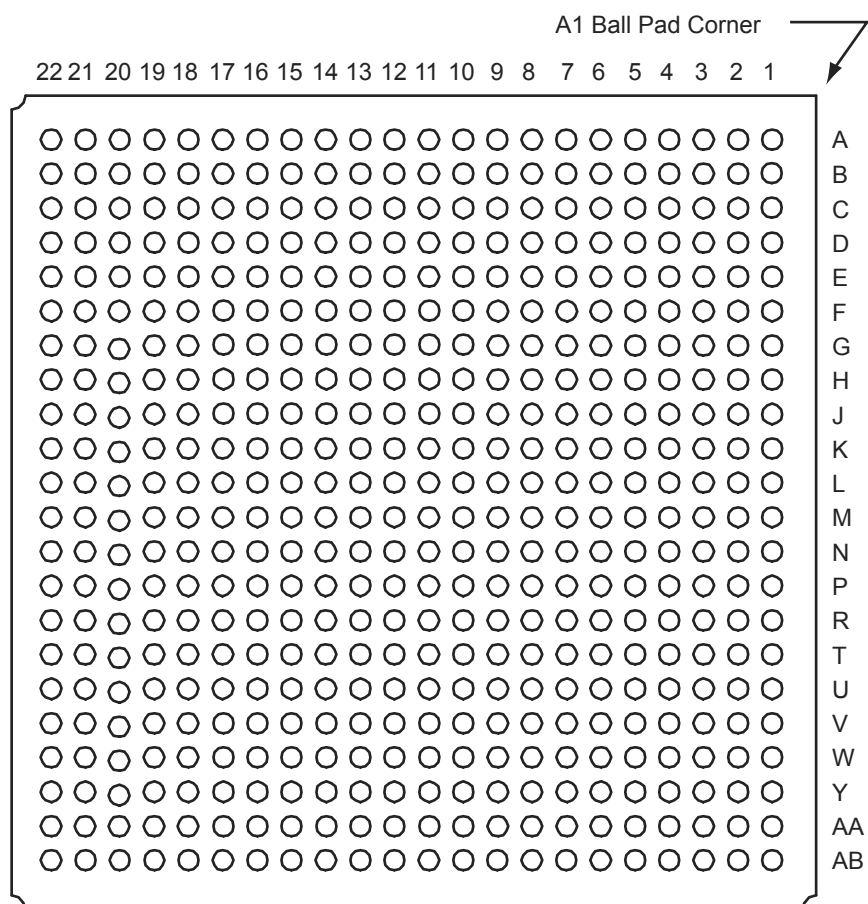
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FG256-Pin FBGA		FG256-Pin FBGA		FG256-Pin FBGA	
AX125 Function	Pin Number	AX125 Function	Pin Number	AX125 Function	Pin Number
Bank 0		IO20NB2F2	F15	IO41PB3F3	L14
IO01NB0F0	B4	IO20PB2F2	E15	Bank 4	
IO01PB0F0	B3	IO21NB2F2	C16	IO42NB4F4	N12
IO03NB0F0	A4	IO21PB2F2	B16	IO42PB4F4	N13
IO03PB0F0	A3	IO22NB2F2	H13	IO43NB4F4	T14
IO04NB0F0	B6	IO22PB2F2	G13	IO43PB4F4	R14
IO04PB0F0	B5	IO23NB2F2	E16	IO44PB4F4	T15
IO06NB0F0	A6	IO23PB2F2	D16	IO45NB4F4	R12
IO06PB0F0	A5	IO25NB2F2	H15	IO45PB4F4	R13
IO07NB0F0/HCLKAN	B8	IO25PB2F2	G15	IO46NB4F4	P11
IO07PB0F0/HCLKAP	B7	IO26NB2F2	H14	IO46PB4F4	P12
IO08NB0F0/HCLKBN	A9	IO26PB2F2	G14	IO47PB4F4	T11
IO08PB0F0/HCLKBP	A8	IO27NB2F2	G16	IO48NB4F4	T12
Bank 1		IO27PB2F2	F16	IO48PB4F4	T13
IO09NB1F1/HCLKCN	C10	IO28NB2F2	K15	IO49NB4F4/CLKEN	R9
IO09PB1F1/HCLKCP	C9	IO28PB2F2	K16	IO49PB4F4/CLKEP	R10
IO10NB1F1/HCLKDN	B11	IO29NB2F2	J16	IO50NB4F4/CLKFN	T8
IO10PB1F1/HCLKDP	B10	IO29PB2F2	H16	IO50PB4F4/CLKFP	T9
IO12NB1F1	A13	Bank 3		Bank 5	
IO12PB1F1	A12	IO30NB3F3	K13	IO51NB5F5/CLKGN	P7
IO13NB1F1	B13	IO30PB3F3	J13	IO51PB5F5/CLKGP	P8
IO13PB1F1	B12	IO31NB3F3	K14	IO52NB5F5/CLKHN	R6
IO14NB1F1	C12	IO31PB3F3	J14	IO52PB5F5/CLKHP	R7
IO14PB1F1	C11	IO33NB3F3	L15	IO54NB5F5	T5
IO15NB1F1	A15	IO33PB3F3	L16	IO54PB5F5	T6
IO15PB1F1	B14	IO35NB3F3	P16	IO55NB5F5	P5
IO16NB1F1	C15	IO35PB3F3	N16	IO55PB5F5	P6
IO16PB1F1	C14	IO36PB3F3	M16	IO56NB5F5	T3
IO17NB1F1	D13	IO37NB3F3	P15	IO56PB5F5	T4
IO17PB1F1	D12	IO37PB3F3	R16	IO57NB5F5	R3
Bank 2		IO39NB3F3	N15	IO57PB5F5	R4
IO18NB2F2	F13	IO39PB3F3	M15	IO58NB5F5	R1
IO18PB2F2	E13	IO40NB3F3	M13	IO58PB5F5	T2
IO19NB2F2	F14	IO40PB3F3	L13	IO59NB5F5	N4
IO19PB2F2	E14	IO41NB3F3	M14	IO59PB5F5	N5

FG256-Pin FBGA	
AX125 Function	Pin Number
VCCA	L10
VCCA	L7
VCCA	L8
VCCA	L9
VCCA	N3
VCCA	P14
VCCPLA	C7
VCCPLB	D6
VCCPLC	A10
VCCPLD	D10
VCCPLE	P10
VCCPLF	N11
VCCPLG	T7
VCCPLH	N7
VCCDA	A2
VCCDA	C13
VCCDA	D9
V _{CCDA}	H1
VCCDA	J15
VCCDA	N14
VCCDA	N8
VCCDA	P4
VCCIB0	E6
VCCIB0	E7
VCCIB0	E8
VCCIB1	E10
VCCIB1	E11
VCCIB1	E9
VCCIB2	F12
VCCIB2	G12
VCCIB2	H12
VCCIB3	J12
VCCIB3	K12
VCCIB3	L12
VCCIB4	M10

FG256-Pin FBGA	
AX125 Function	Pin Number
VCCIB4	M11
VCCIB4	M9
VCCIB5	M6
VCCIB5	M7
VCCIB5	M8
VCCIB6	J5
VCCIB6	K5
VCCIB6	L5
VCCIB7	F5
VCCIB7	G5
VCCIB7	H5
VCOMPLA	A7
VCOMPLB	D7
VCOMPLC	B9
VCOMPLD	D11
VCOMPLE	T10
VCOMPLF	N10
VCOMPLG	R8
VCOMPLH	N6
VPUMP	A14

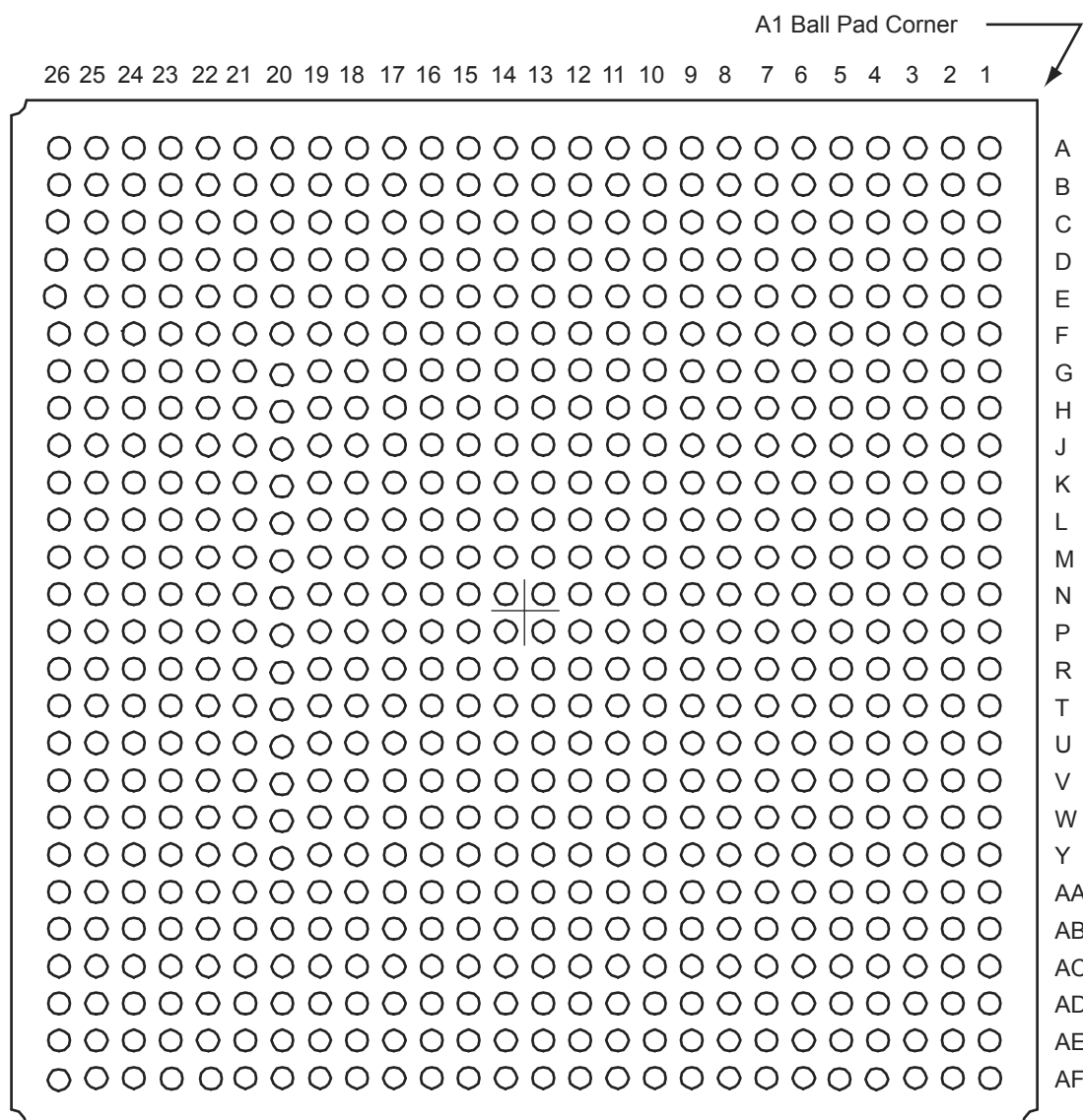
FG484



Note

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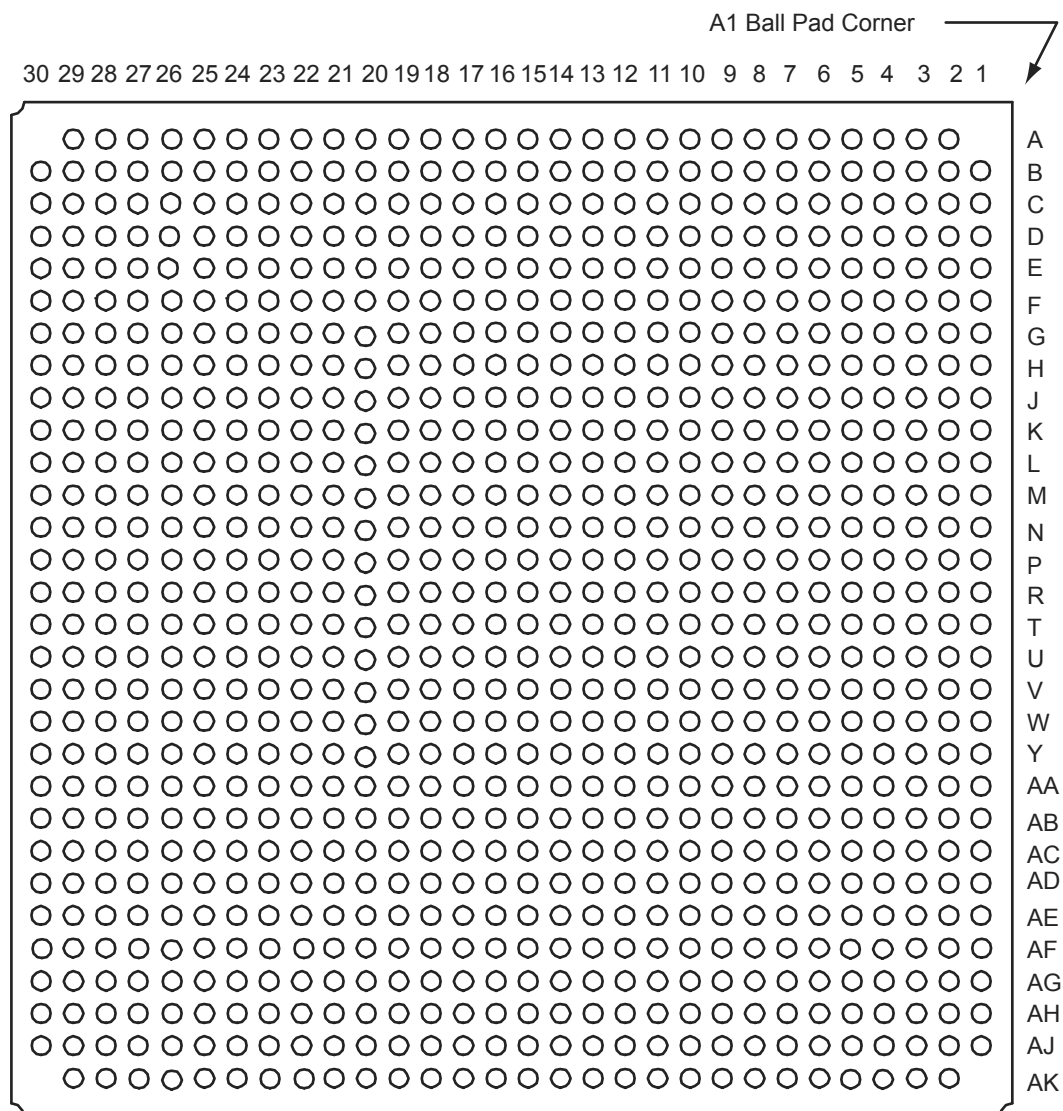
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Note

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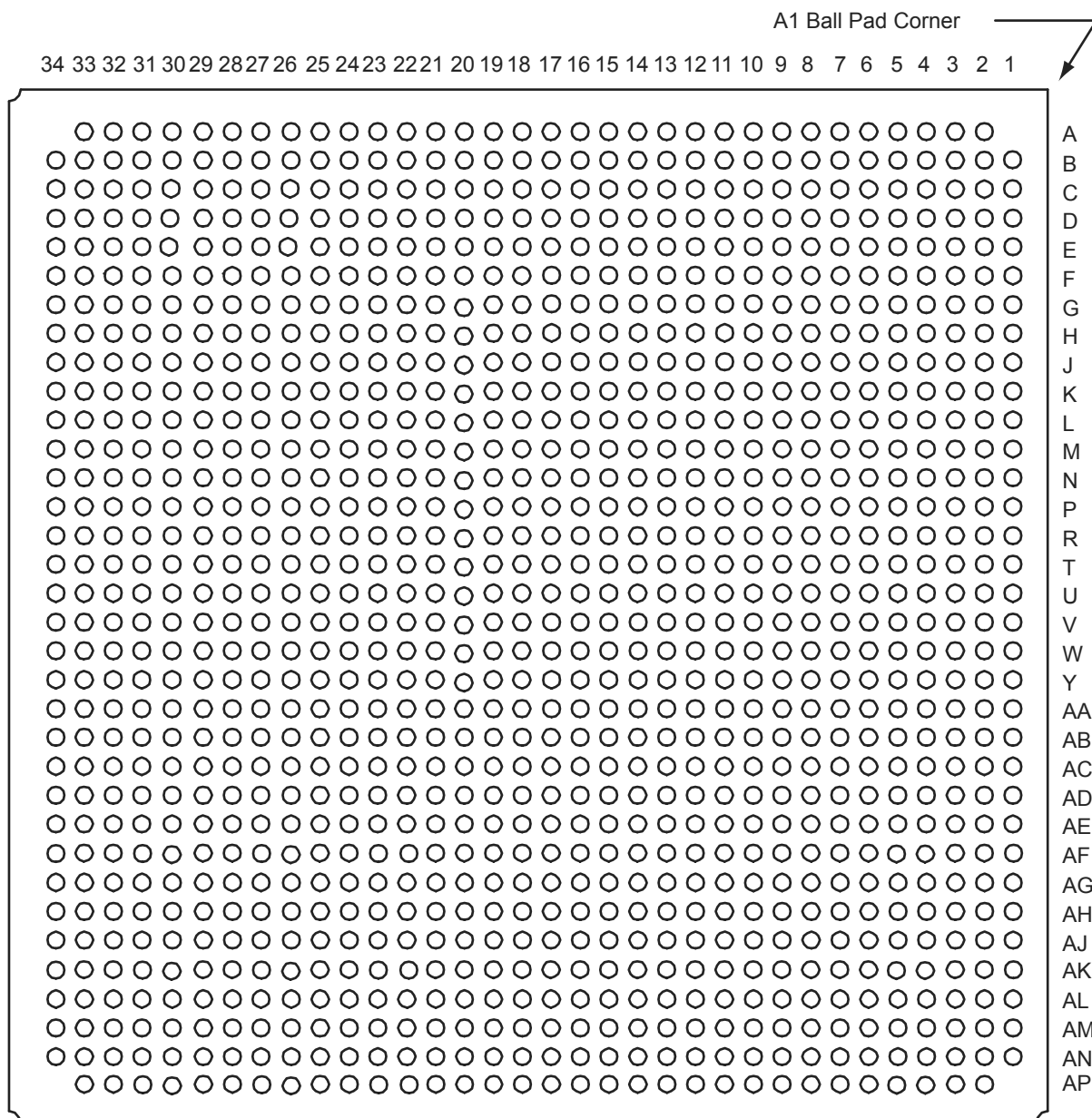
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Note

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FG1152

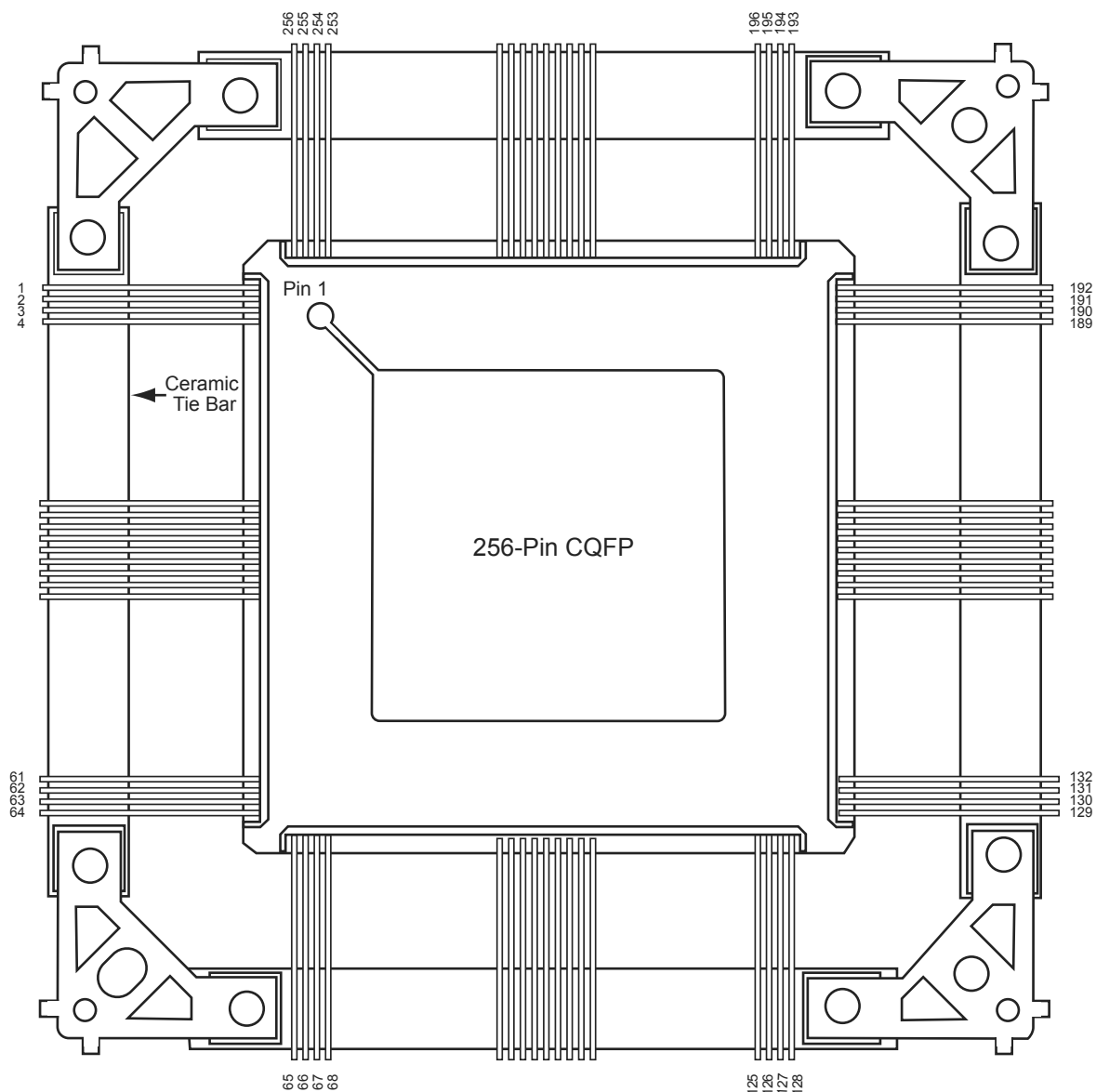


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FG1152		FG1152		FG1152	
AX2000 Function	Pin Number	AX2000 Function	Pin Number	AX2000 Function	Pin Number
VCCIB0	C5	VCCIB3	AA24	VCCIB6	AA11
VCCIB0	D5	VCCIB3	AB23	VCCIB6	AA12
VCCIB0	L12	VCCIB3	AB24	VCCIB6	AB11
VCCIB0	L13	VCCIB3	AC24	VCCIB6	AB12
VCCIB0	L14	VCCIB3	AK31	VCCIB6	AC11
VCCIB0	M13	VCCIB3	AK32	VCCIB6	AK1
VCCIB0	M14	VCCIB3	AK33	VCCIB6	AK2
VCCIB0	M15	VCCIB3	AK34	VCCIB6	AK3
VCCIB0	M16	VCCIB3	V23	VCCIB6	AK4
VCCIB0	M17	VCCIB3	W23	VCCIB6	V12
VCCIB1	A30	VCCIB3	Y23	VCCIB6	W12
VCCIB1	B30	VCCIB4	AC18	VCCIB6	Y12
VCCIB1	C30	VCCIB4	AC19	VCCIB7	E1
VCCIB1	D30	VCCIB4	AC20	VCCIB7	E2
VCCIB1	L21	VCCIB4	AC21	VCCIB7	E3
VCCIB1	L22	VCCIB4	AC22	VCCIB7	E4
VCCIB1	L23	VCCIB4	AD21	VCCIB7	M11
VCCIB1	M18	VCCIB4	AD22	VCCIB7	N11
VCCIB1	M19	VCCIB4	AD23	VCCIB7	N12
VCCIB1	M20	VCCIB4	AL30	VCCIB7	P11
VCCIB1	M21	VCCIB4	AM30	VCCIB7	P12
VCCIB1	M22	VCCIB4	AN30	VCCIB7	R12
VCCIB2	E31	VCCIB4	AP30	VCCIB7	T12
VCCIB2	E32	VCCIB5	AC13	VCCIB7	U12
VCCIB2	E33	VCCIB5	AC14	VCCPLA	J16
VCCIB2	E34	VCCIB5	AC15	VCCPLB	K17
VCCIB2	M24	VCCIB5	AC16	VCCPLC	J19
VCCIB2	N23	VCCIB5	AC17	VCCPLD	L18
VCCIB2	N24	VCCIB5	AD12	VCCPLE	AK19
VCCIB2	P23	VCCIB5	AD13	VCCPLF	AE18
VCCIB2	P24	VCCIB5	AD14	VCCPLG	AK16
VCCIB2	R23	VCCIB5	AL5	VCCPLH	AF17
VCCIB2	T23	VCCIB5	AM5	VCOMPLA	H16
VCCIB2	U23	VCCIB5	AN5	VCOMPLB	L17
VCCIB3	AA23	VCCIB5	AP5	VCOMPLC	H19

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Note

For Package Manufacturing and Environmental information, visit the Resource center at <http://www.microsemi.com/soc/products/solutions/package/docs.aspx>.

CQ352		CQ352		CQ352	
AX1000 Function	Pin Number	AX1000 Function	Pin Number	AX1000 Function	Pin Number
Bank 0		IO60NB1F5	275	Bank 3	
IO02NB0F0	341	IO60PB1F5	276	IO96NB3F9	217
IO02PB0F0	342	IO61NB1F5	271	IO96PB3F9	218
IO03PB0F0	343	IO61PB1F5	272	IO97NB3F9	219
IO04NB0F0	337	IO63NB1F5	269	IO97PB3F9	220
IO04PB0F0	338	IO63PB1F5	270	IO99NB3F9	213
IO08NB0F0	331	Bank 2		IO99PB3F9	214
IO08PB0F0	332	IO64NB2F6	259	IO108NB3F10	211
IO09NB0F0	335	IO64PB2F6	260	IO108PB3F10	212
IO09PB0F0	336	IO67NB2F6	261	IO109NB3F10	207
IO24NB0F2	325	IO67PB2F6	262	IO109PB3F10	208
IO24PB0F2	326	IO68NB2F6	255	IO111NB3F10	205
IO25NB0F2	323	IO68PB2F6	256	IO111PB3F10	206
IO25PB0F2	324	IO69NB2F6	253	IO112NB3F10	199
IO30NB0F2/HCLKAN	319	IO69PB2F6	254	IO112PB3F10	200
IO30PB0F2/HCLKAP	320	IO74NB2F7	249	IO113NB3F10	201
IO31NB0F2/HCLKBN	313	IO74PB2F7	250	IO113PB3F10	202
IO31PB0F2/HCLKBP	314	IO75NB2F7	247	IO115NB3F10	195
Bank 1		IO75PB2F7	248	IO115PB3F10	196
IO32NB1F3/HCLKCN	305	IO76NB2F7	243	IO116NB3F10	193
IO32PB1F3/HCLKCP	306	IO76PB2F7	244	IO116PB3F10	194
IO33NB1F3/HCLKDN	299	IO77NB2F7	241	IO117NB3F10	189
IO33PB1F3/HCLKDP	300	IO77PB2F7	242	IO117PB3F10	190
IO38NB1F3	295	IO78NB2F7	237	IO124NB3F11	183
IO38PB1F3	296	IO78PB2F7	238	IO124PB3F11	184
IO54NB1F5	287	IO79NB2F7	235	IO125NB3F11	187
IO54PB1F5	288	IO79PB2F7	236	IO125PB3F11	188
IO55NB1F5	289	IO82NB2F7	231	IO127NB3F11	181
IO55PB1F5	290	IO82PB2F7	232	IO127PB3F11	182
IO56NB1F5	281	IO83NB2F7	229	IO128NB3F11	179
IO56PB1F5	282	IO83PB2F7	230	IO128PB3F11	180
IO57NB1F5	283	IO94NB2F8	225	Bank 4	
IO57PB1F5	284	IO94PB2F8	226	IO130NB4F12	172
IO59NB1F5	277	IO95NB2F8	223	IO130PB4F12	173
IO59PB1F5	278	IO95PB2F8	224	IO131NB4F12	170